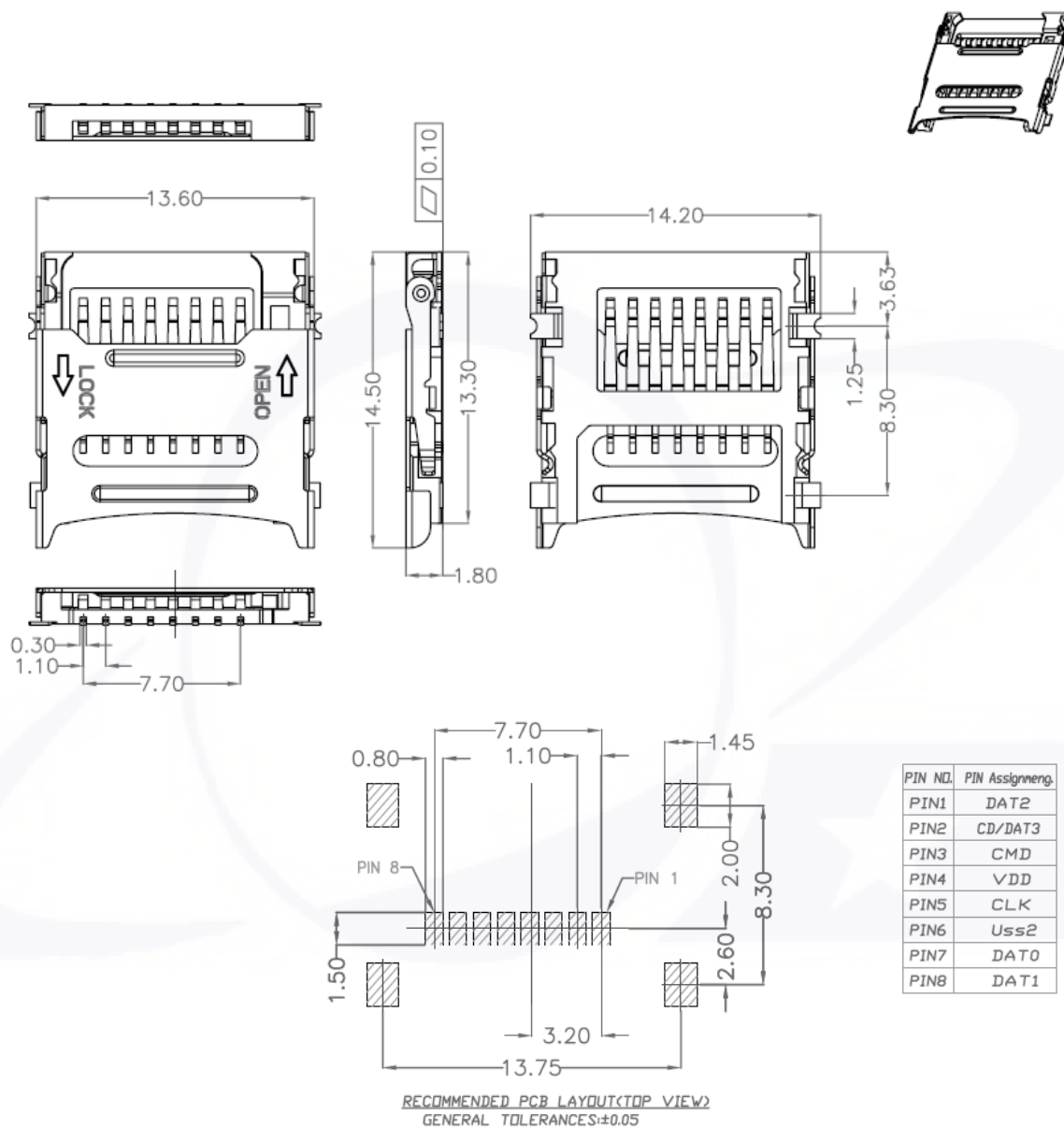


MICRO SD (T-FLASH) PCB MOUNT, SMT, METAL SHIELD, FEMALE, HINGE TYPE
MATERIALS

HOUSING: HI-TEMP. PLASTIC, UL 94V-0
 SHELL: STAINLESS STEEL
 SOLDER PAD: COPPER ALLOY, TIN PLATING
 TERMINAL: COPPER ALLOY, GOLD PLATED ON CONTACT AREA
 TIN PLATING ON SOLDER TAIL

SPECIFICATION

CURRENT RATING: 0.5 AMP MAX
 DIELECTRIC WITHSTANDING: 500V AC FOR ONE MINUTE
 CONTACT RESISTANCE: 100m OHMS MAX
 INSULATION RESISTANCE: 1000M OHMS MIN AT DC 500V
 OPERATION TEMPERATURE: -20°C ~ +60°C



Series NO.	Free Code	NO. of Pos.	Contact	Contact Plating
SDT-	2-	08	[2] SMT	[G1] Gold Flash